

## 모집분야 및 세부업무

구 분	채 용 분 야
<b>Package / Process Technology</b>	<ul style="list-style-type: none"> <li>· 3D Package, Flip Chip/Wafer Level Package (WLP/TSV etc.)</li> <li>· Package Material(Film, Solder, PCB, etc.)</li> <li>· Particle/Contamination/Void Control, PKG Reliability Analysis</li> <li>· Package/Chip Warpage Control, Thermal Distortion Control</li> <li>· Micro Solder Bump, Welding Reliability</li> <li>· Vision, Laser Application(Cutting, Marking, Inspection), Plasma</li> <li><input type="checkbox"/> Advanced Process Development</li> <li>· Wafer Handling/Grinding/Thinning, Wire Bonding, Die Attach/Bonding, Wafer Dicing/Sawing, Chip Stack, Molding, Soldering, SMT(Surface Mount Tech.)</li> </ul>
<b>Test Technology / Software</b>	<ul style="list-style-type: none"> <li><input type="checkbox"/> Signal Processing &amp; Test</li> <li>· High Speed Circuit Design</li> <li>· Analog and Mixed Signal Integrated Circuit Design</li> <li>· Digital Signal Processing</li> <li>· Automatic Test Equipment System Design</li> <li>· Power System, Power Electronics</li> <li>· Design for Test(DFT)</li> <li><input type="checkbox"/> SW</li> <li>· Database design, Optimization</li> <li>· Data mining, Algorithm, Statistic Analysis</li> <li>· Software Optimization</li> <li>· Embedded(Firmware) Programming</li> <li>· Heuristic Roution</li> <li>· Job Scheduling Algorithm</li> </ul>
<b>Equipment Development</b>	<ul style="list-style-type: none"> <li><input type="checkbox"/> CAE Analysis</li> <li>· Structure, Dynamics, Thermal, Fluid Analysis/CFD</li> <li><input type="checkbox"/> Robot &amp; System Integration</li> <li>· Robotics, Dynamics &amp; Kinematics</li> <li>· Optimal Design / Robust Design</li> <li>· Sensor &amp; Actuator Technology</li> <li><input type="checkbox"/> Control</li> <li>· Motion Control, Vibration Control</li> <li>· High Rigidity/high Precision/high Accuracy Control</li> </ul>

	<ul style="list-style-type: none"> <li>· Thermal Compensation Algorithm</li> <li><input type="checkbox"/> SW <ul style="list-style-type: none"> <li>· Real time OS System Programming</li> <li>· Embedded System Programming</li> <li>· Intelligent SW Architecture</li> <li>· Industrial Software Engineering</li> </ul> </li> <li><input type="checkbox"/> Mold <ul style="list-style-type: none"> <li>· Injection Mold Design</li> <li>· Molding Technology</li> <li>· Press Die Design/ Mold Materials</li> </ul> </li> </ul>
<b>Vision System</b>	<ul style="list-style-type: none"> <li><input type="checkbox"/> Optics &amp; Inspection <ul style="list-style-type: none"> <li>· Precision Optical System Design</li> <li>· Image Processing Algorithm</li> <li>· 2D/3D Image based Measurement</li> <li>· X-ray Computed Tomography</li> </ul> </li> </ul>
<b>Automation</b>	<ul style="list-style-type: none"> <li>· FMS(Flexible Manufacturing System)</li> <li>· Automation System Simulation</li> <li>· Manufacturing System Analysis/Assessment/Design</li> <li>· Conveying System Design/Control</li> <li>· Manufacturing Line Layout Design</li> <li>· AutoMod(Simulation Software) Skills</li> </ul>
<b>Quality &amp; Reliability</b>	<ul style="list-style-type: none"> <li>· Data Analysis &amp; Statistic Analysis</li> <li>· SPC(Statistical Process Control), Multivariate Statistical Analysis</li> <li>· Data Mining Application(for Manufacturing, Quality/Reliability)</li> <li>· Database OLAP(Online Analytical Processing) Analysis</li> <li>· Design For Reliability, QFD.</li> <li>· Process Quality Design.</li> <li>· FDC, APC, VMS Logic Development, Advanced Quality System Design</li> <li>· Measuring Sensor Development, Monitoring Method/Tool Development</li> </ul>

※ 근무지 : 삼성전자 나노시티 Test&Package 센터(충남 아산 소재)